



WAH LEE INDUSTRIAL CORP.

華立企業股份有限公司

Material Pioneer, Technology Navigator



INVESTOR MEETING

法說簡報

June 2014

2014年6月

TSE Ticker : 3010 TT

<http://www.wahlee.com>

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合併2013年營運報告

Company Profile 公司簡介

Inception: 10/1/1968

成立日期

Listing: 9/22/2002 on TSE(台灣證券交易所)

掛牌日期

Capital: NT\$ 2,313,901,380

實收資本額

Market Cap: ~USD\$450 million

市值

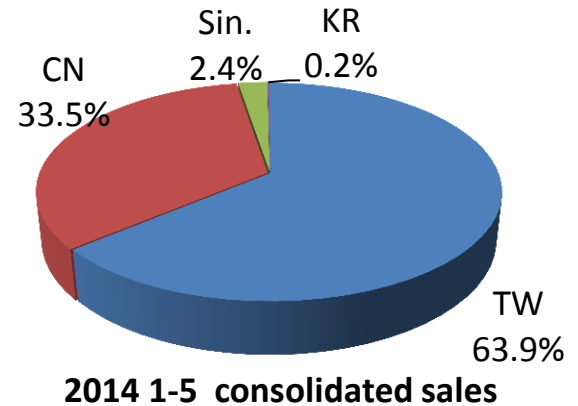
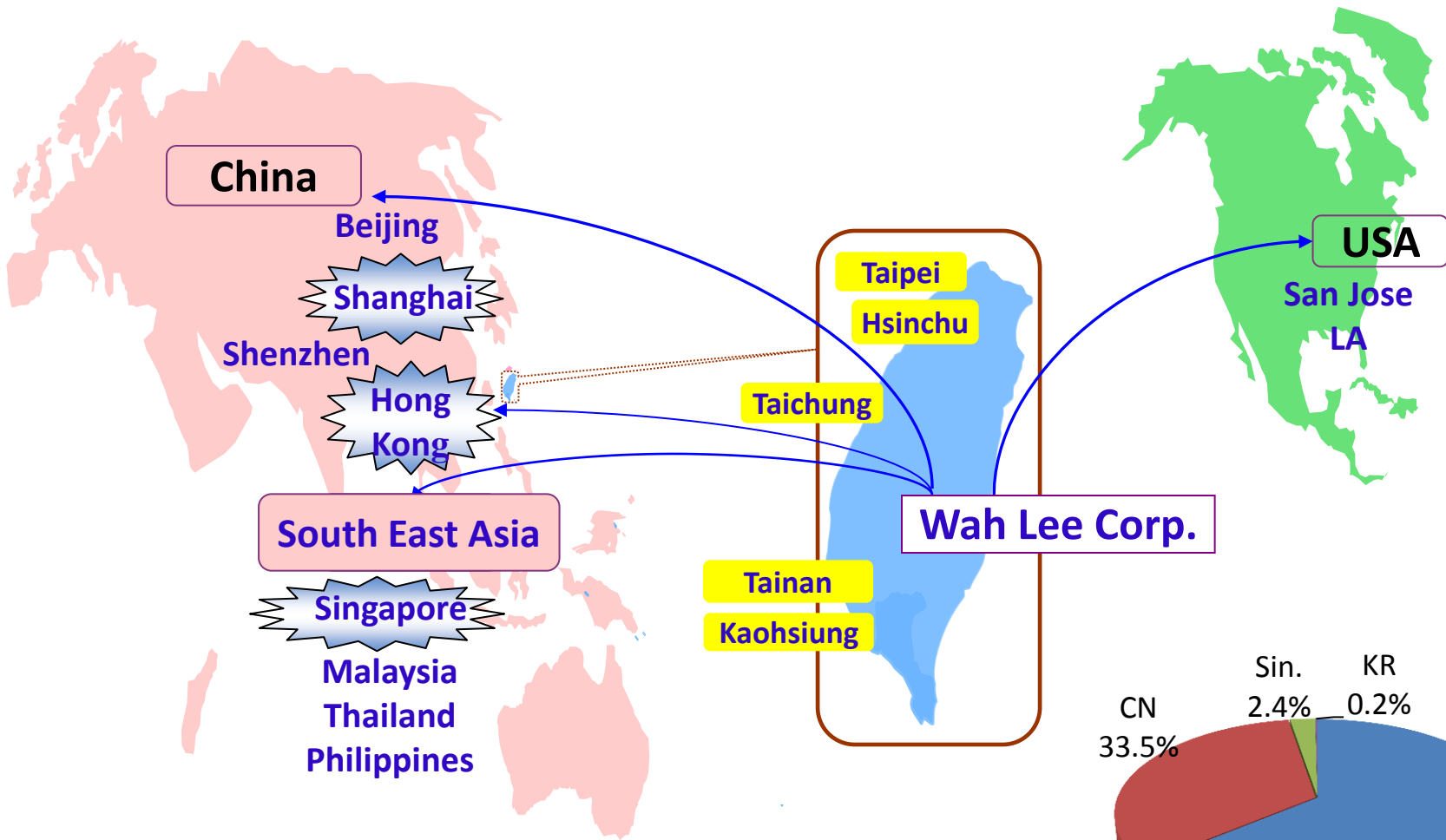
Core Business: Leading HI-TECH solutions integrator and raw

主要業務

materials provider for :

- Computer & Communication
- Semiconductor
- FPD
- Green Energy/Optoelectronics

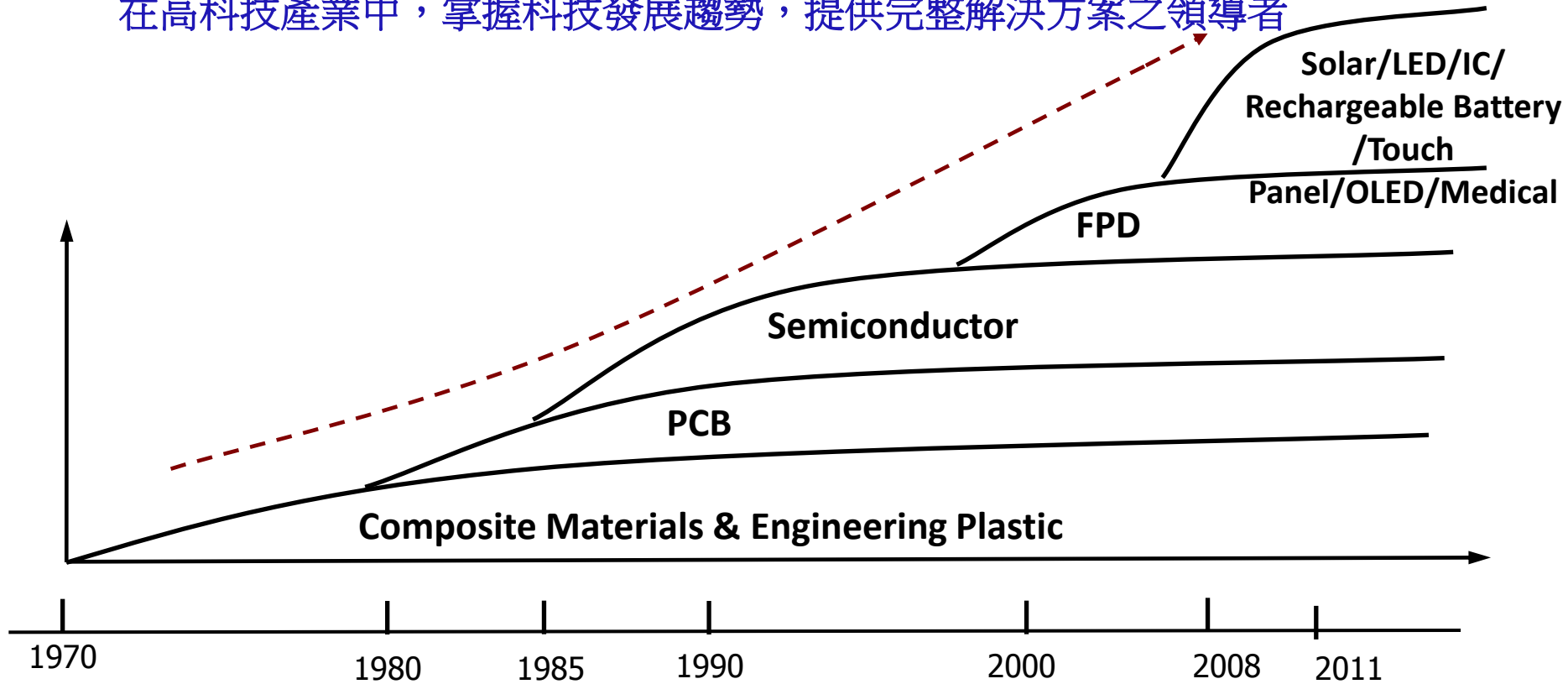
Sales Offices 國際行銷據點



Wah Lee's Core Competence 華立核心競爭力

- I. Leader in foreseeing technology developments and solutions provider of upstream raw materials & equipment in high-tech industries

在高科技產業中，掌握科技發展趨勢，提供完整解決方案之領導者



- II. Developing Next Generation Technologies:

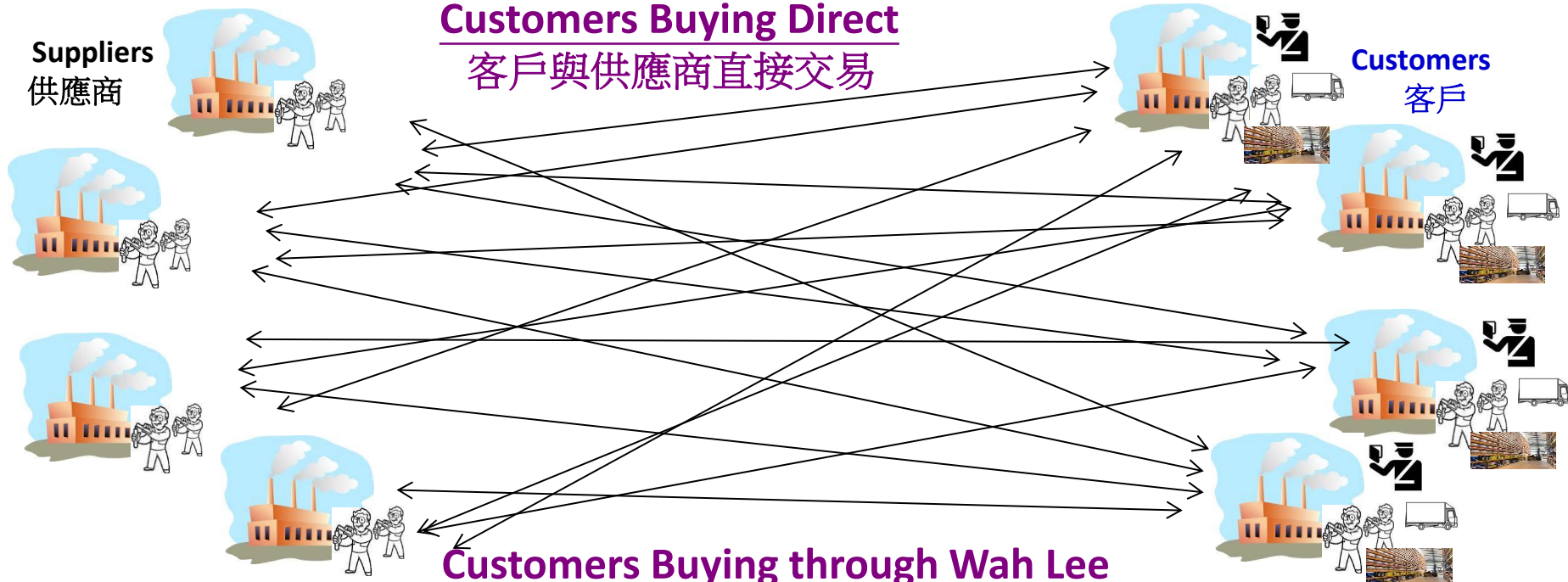
投資開發下一代明星產業，如先進顯示技術，固態照明，太陽能發電，電動車等

- Advanced displays (3D, flexible, transparent...)
- Solid state lighting, advanced solar, electrical vehicle related systems...

Wah Lee's Value Proposition 華立附加價值

Customers Buying Direct

客戶與供應商直接交易



Customers Buying through Wah Lee

華立在供應鏈中提供關鍵附加價值: 一次購足

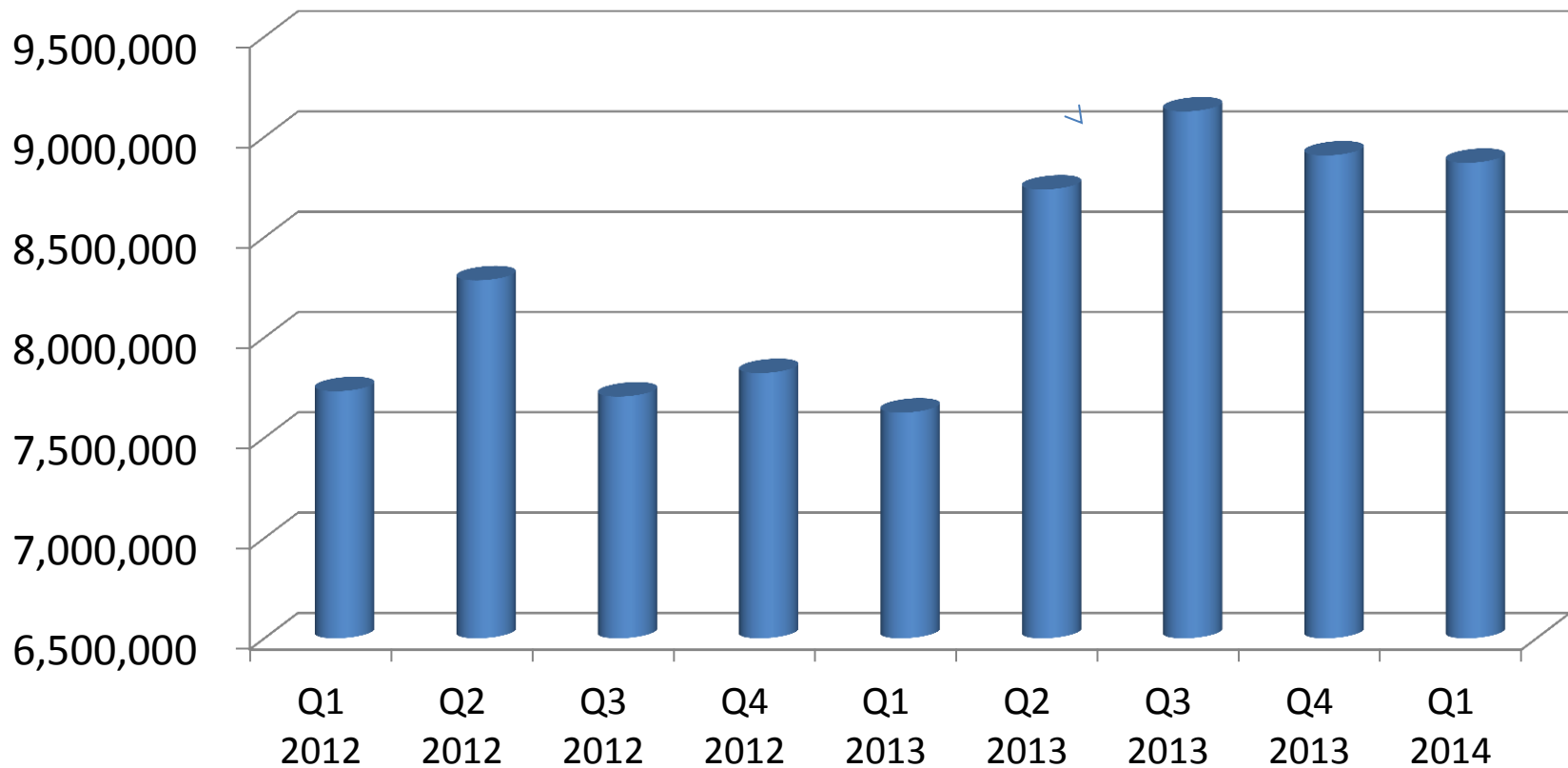


Quarterly Consolidated Sales 季合併營收資訊

季合併營收

Quarterly Consolidated Sales

千元
In thousands

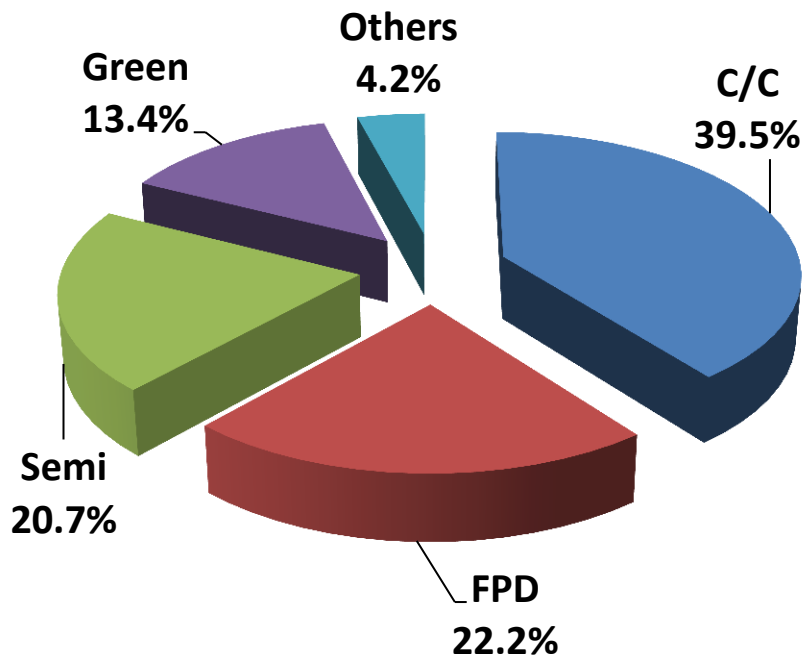


2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1
7,732,183	8,285,087	7,705,533	7,822,470	7,625,467	8,737,837	9,127,265	8,907,828	8,870,920

Industry Sales Breakdown 營收產業別資訊

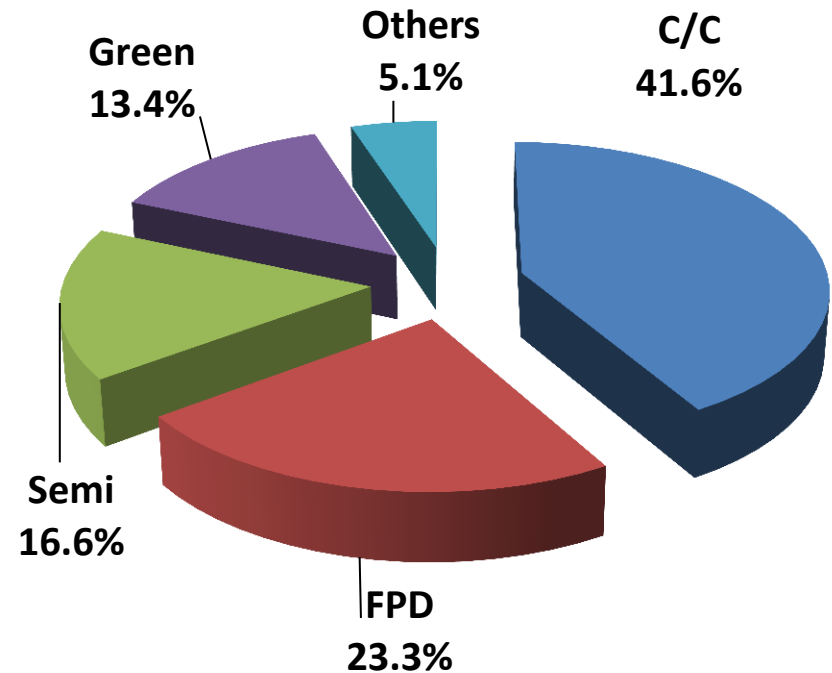
2014/ 01-05

Sales NT\$15.8 Billion



2013/ 01-05

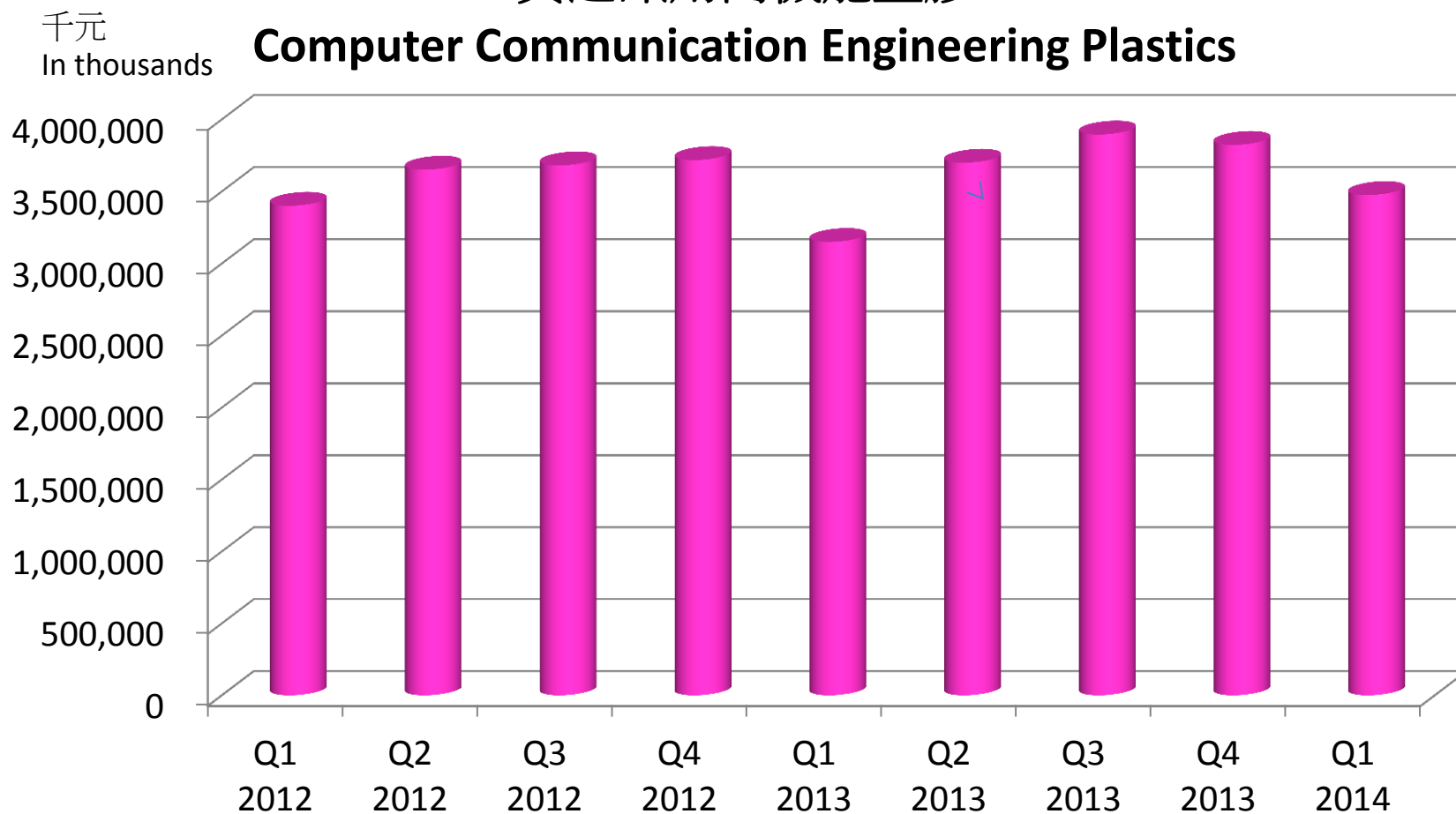
Sales NT\$13.7 Billion



Industry Sales Breakdown : C/C 資通訊營收

資通訊用高機能塑膠

Computer Communication Engineering Plastics

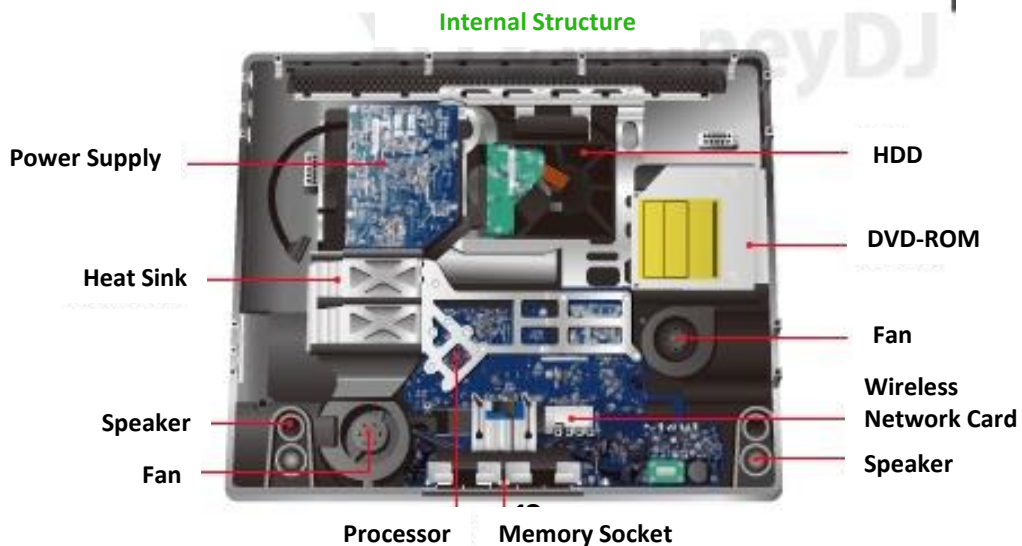
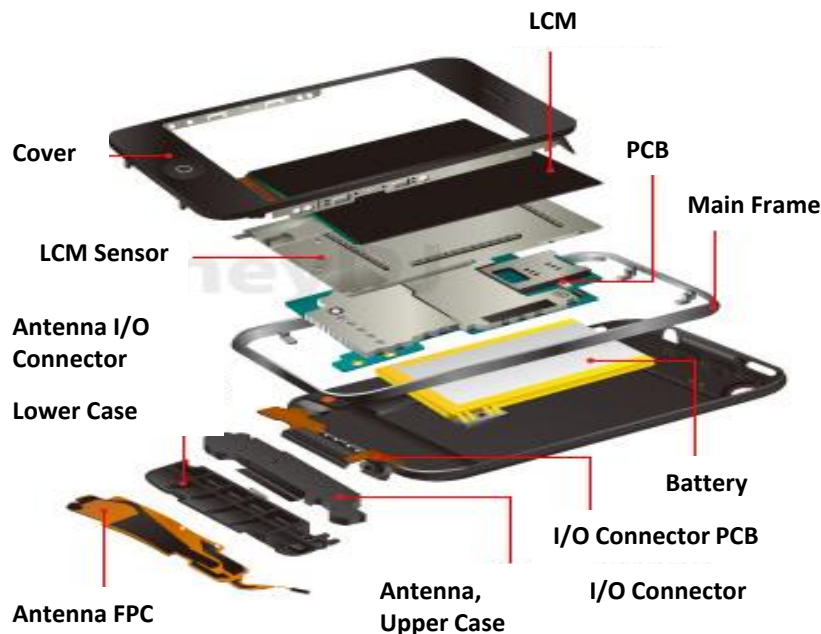


2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1
3,400,729	3,651,344	3,681,425	3,718,072	3,150,057	3,699,583	3,895,425	3,823,343	3,475,523

Products in C/C 資訊通訊產品

High Performance Engineering Plastics

1. Case : Carbon Fiber 、 TORAY CFRP 、 PA
2. Lens : OKP4 、 ARTON 、 Hard Coated Sheet
3. Insulating Strip 、 Battery Label :
PET FILM 、 PC FILM 、 PBT FILM
4. Speaker : PET FILM
5. Charge Station : Phenolic Moulding Compound
6. Connector : LCP 、 PA9T
7. Reflector : PA9T
8. Transformer /PFC: Phenolic Moulding Compound
9. Inverter Bobbin : LCP



高機能工程塑膠近期開發應用領域 1

Recent developments in Engineering Plastics 1



汽車

Pulley, Water
Pump, Piston,
Gasket

照明

LED Cover



家電

Coffee
Machine &
Juicer Parts



高機能工程塑膠近期開發應用領域 2

Recent developments in Engineering Plastics 2



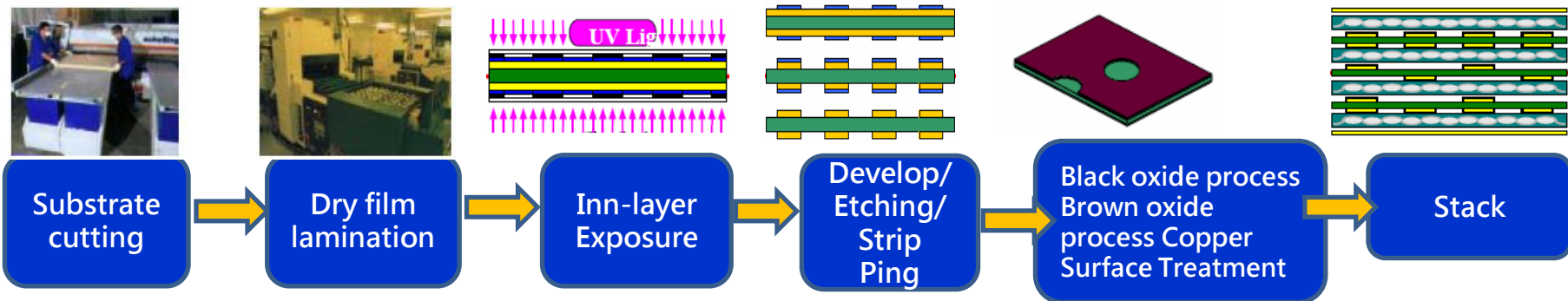
民生消費品
Glasses
Frame

醫療輸液
Medical
Liquid Bags

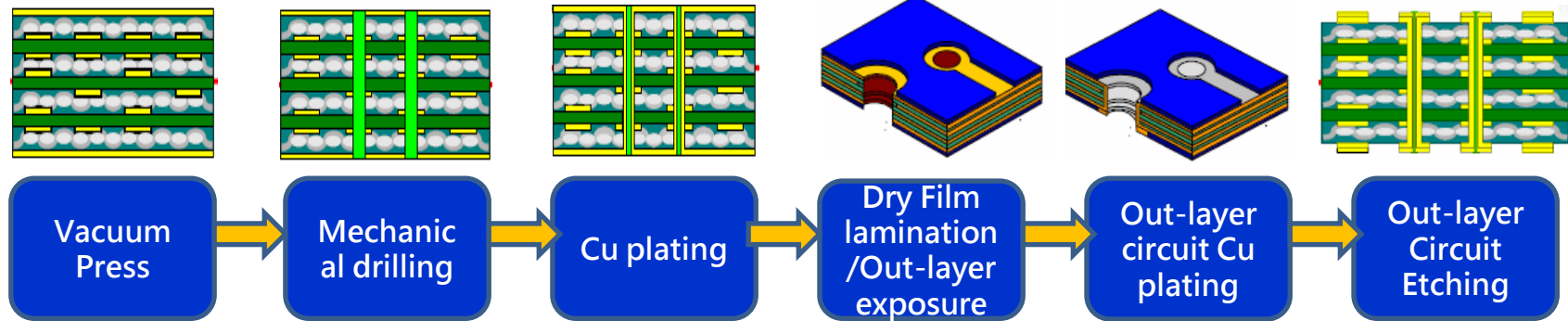


食品包裝
Food
Packaging

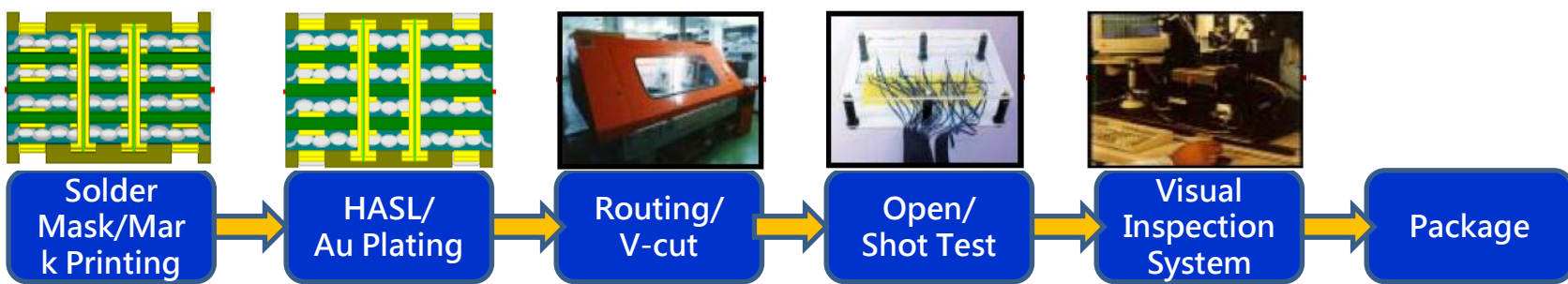
Products in PCB Industry PCB產業產品



- CCL
- Dry Film
- Lamination Machine



- Release Film
- Dry Film

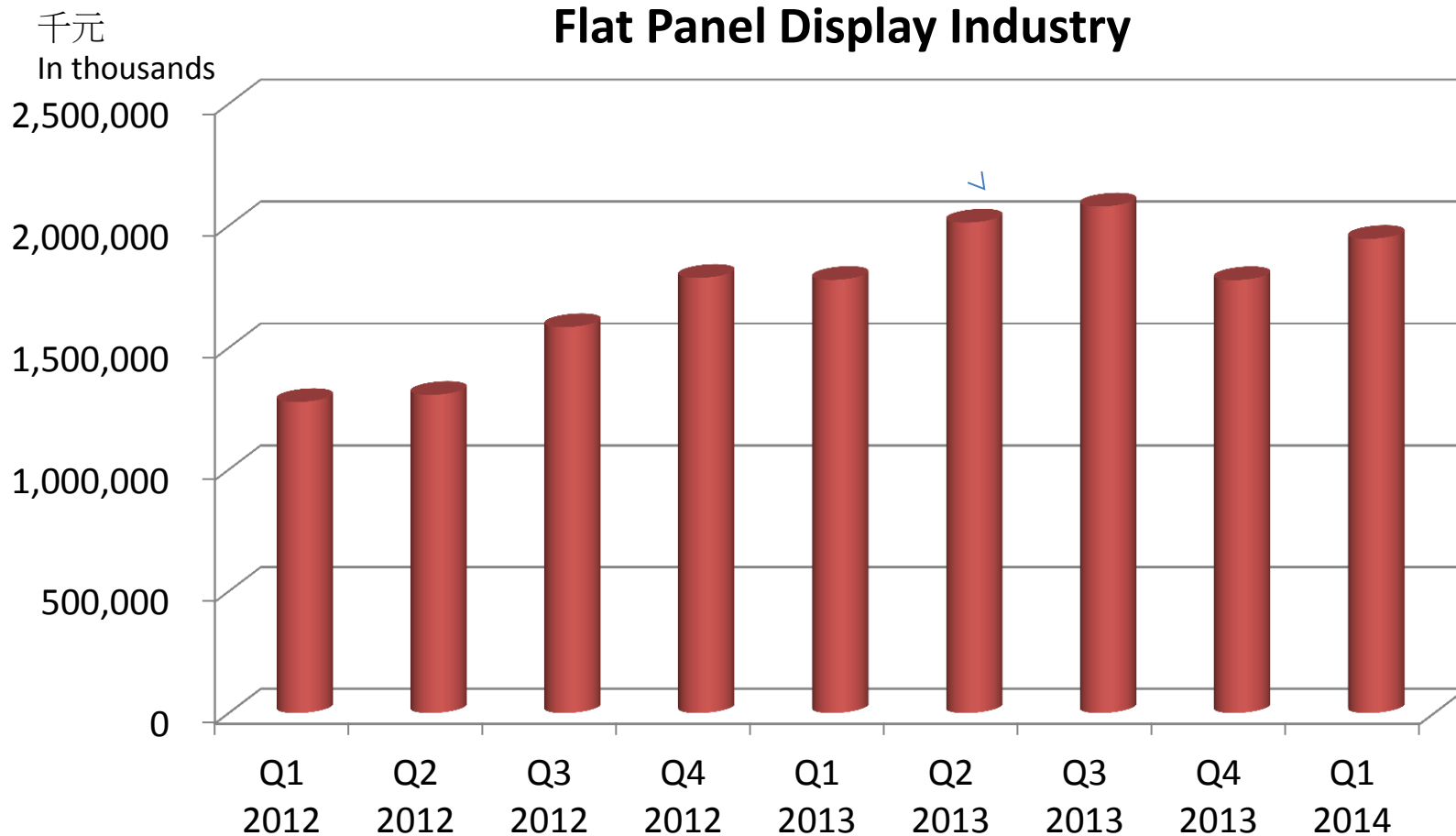


- CNC Router
- Beveling Machine
- AOI
- Screen Visual Inspection

Industry Sales Breakdown: FPD 平面顯示器營收

平面顯示器產業

Flat Panel Display Industry

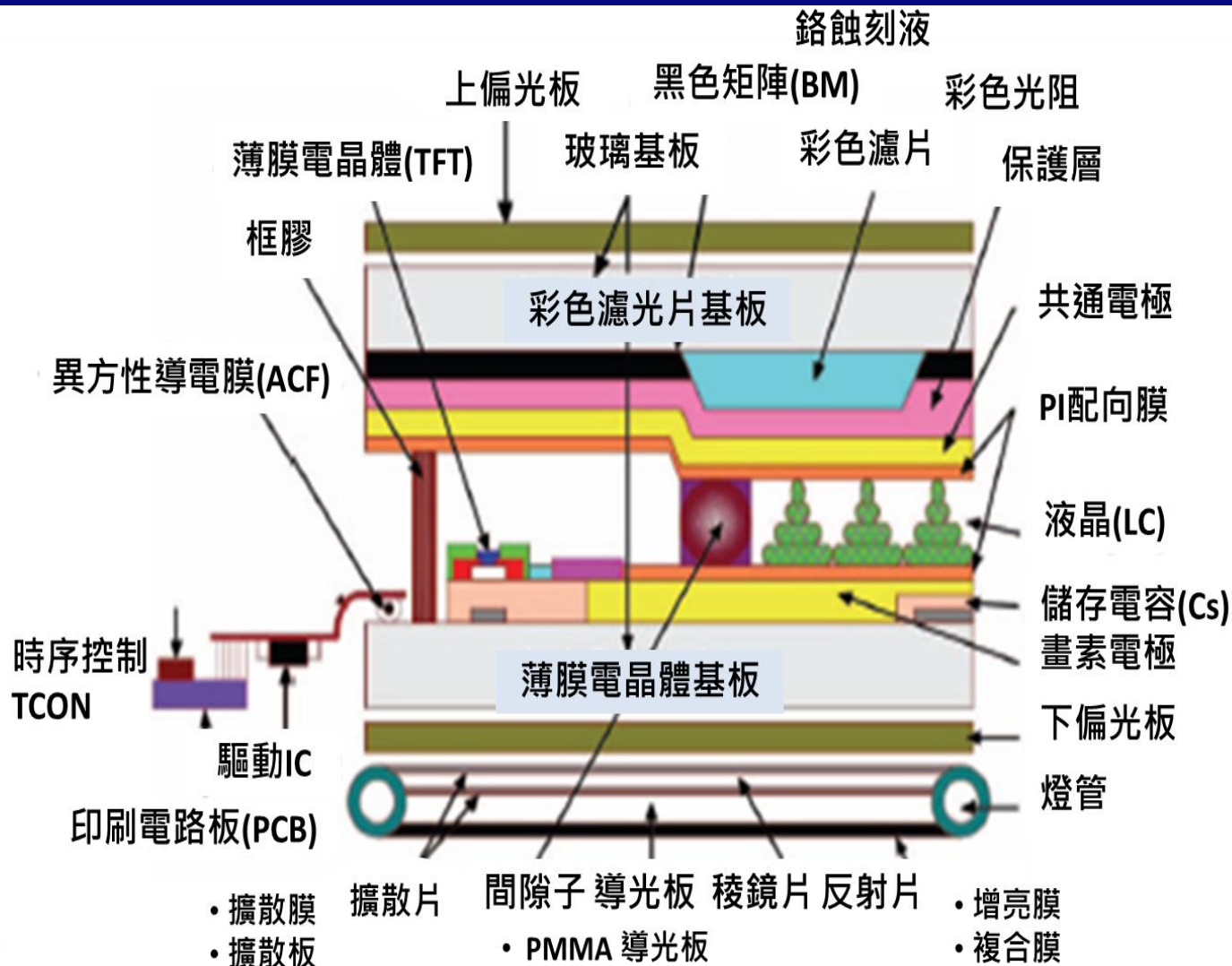


2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1
1,277,309	1,306,531	1,584,445	1,786,398	1,777,895	2,012,892	2,078,850	1,777,002	1,946,111

在LCD TV應用中，華立供應超過九成材料 Wah Lee Provides over 90% of Material used in LCD TV

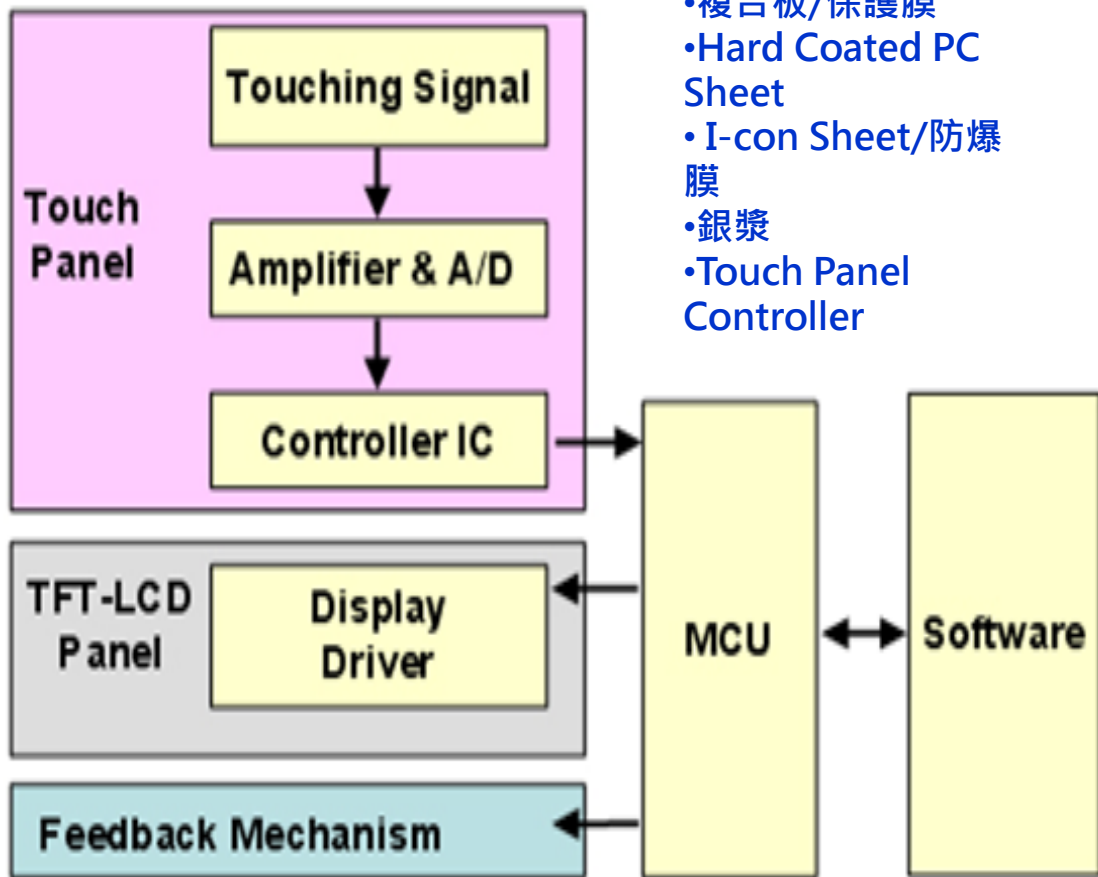
製程設備與耗材
其它製程用化學材
及氣體

- Edge Beam Cleaning : PGME、PGMEA
- Chamber Cleaning : NF3
- 形成 Si 薄膜 : SiH4



在平板與手機應用中，華立提供超過七成材料

Wah Lee Provides over 70% of material used in FPD and Cell Phone



- 複合板/保護膜
- Hard Coated PC Sheet
- I-con Sheet/防爆膜
- 銀漿
- Touch Panel Controller

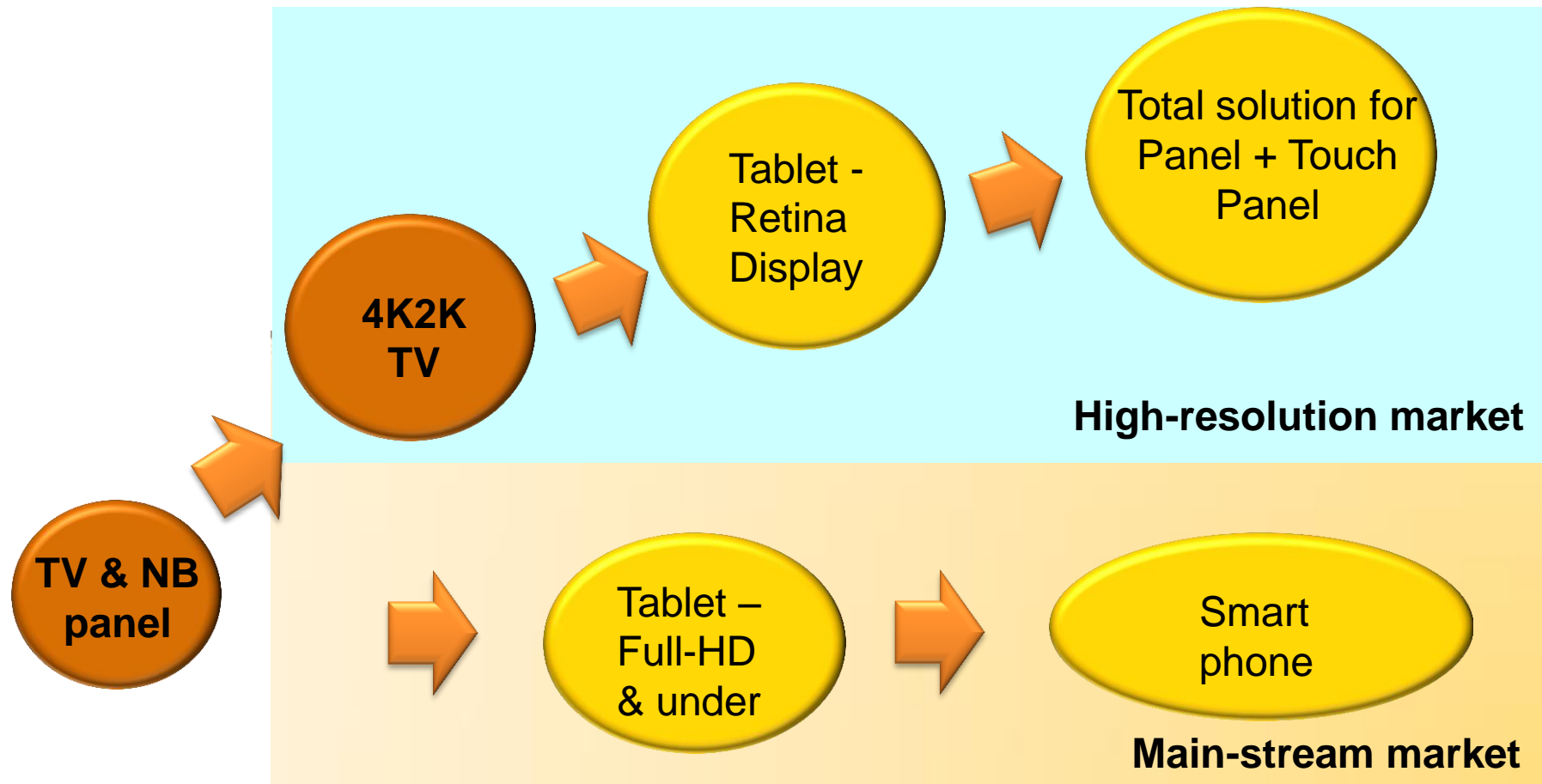


電池材料
Battery
Materials

高機能工程塑膠
High performance
Engineering
Plastics、碳纖維材料
Carbon Fiber...

PCB/軟板材料
PCB/FBC
Materials

FPD Business Development FPD發展計畫



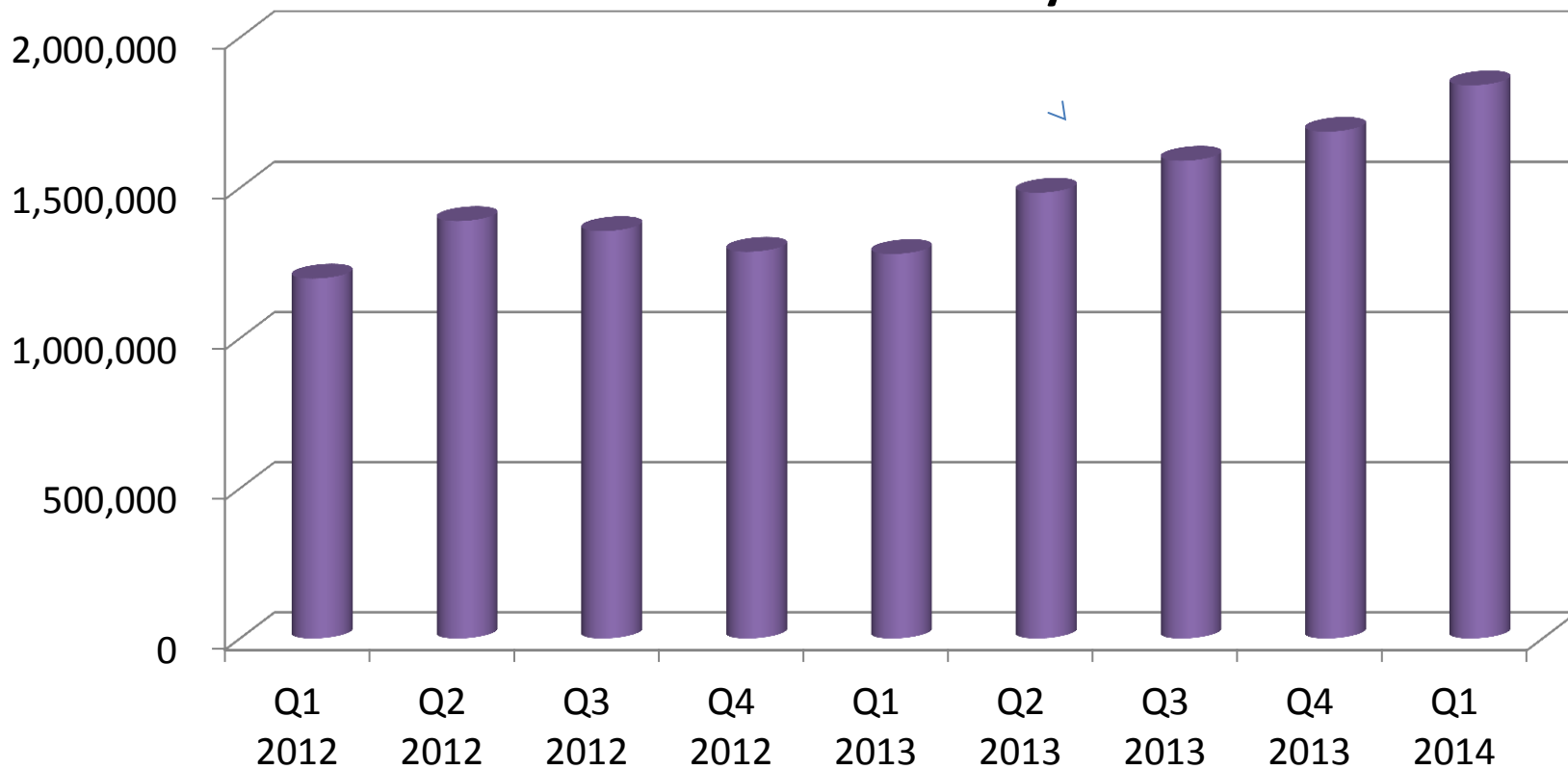
T-con
+ power mgt. IC

Integrated IC (iChip) + power mgt. IC

Industry Sales Breakdown: Semi 半導體營收

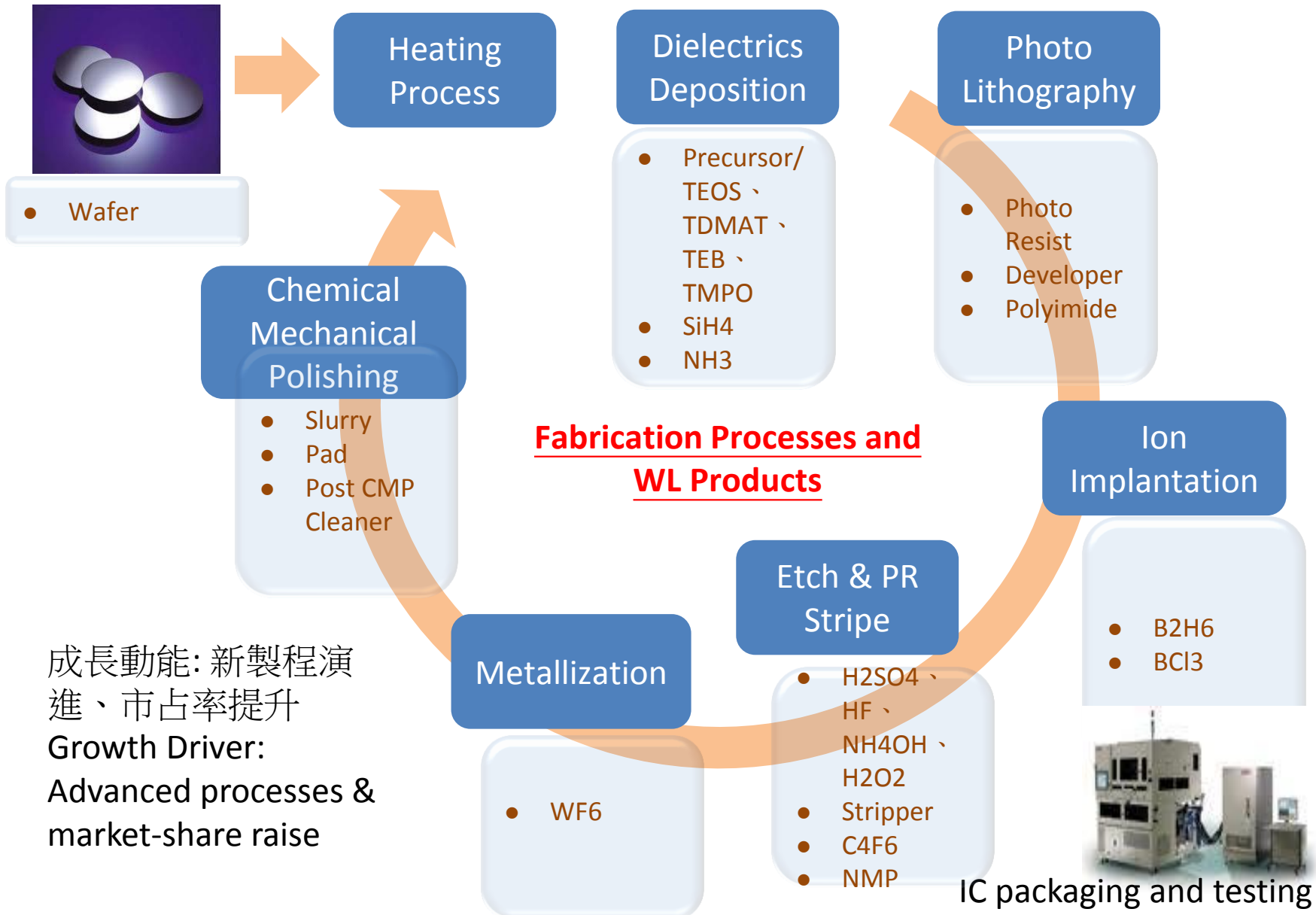
千元
In thousands

半導體產業 Semiconductor Industry



2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1
1,198,674	1,389,833	1,356,480	1,287,735	1,280,269	1,484,104	1,590,222	1,686,773	1,840,960

Semiconductor Supply Chain 半導體供應鏈



成長動能: 新製程演進、市占率提升

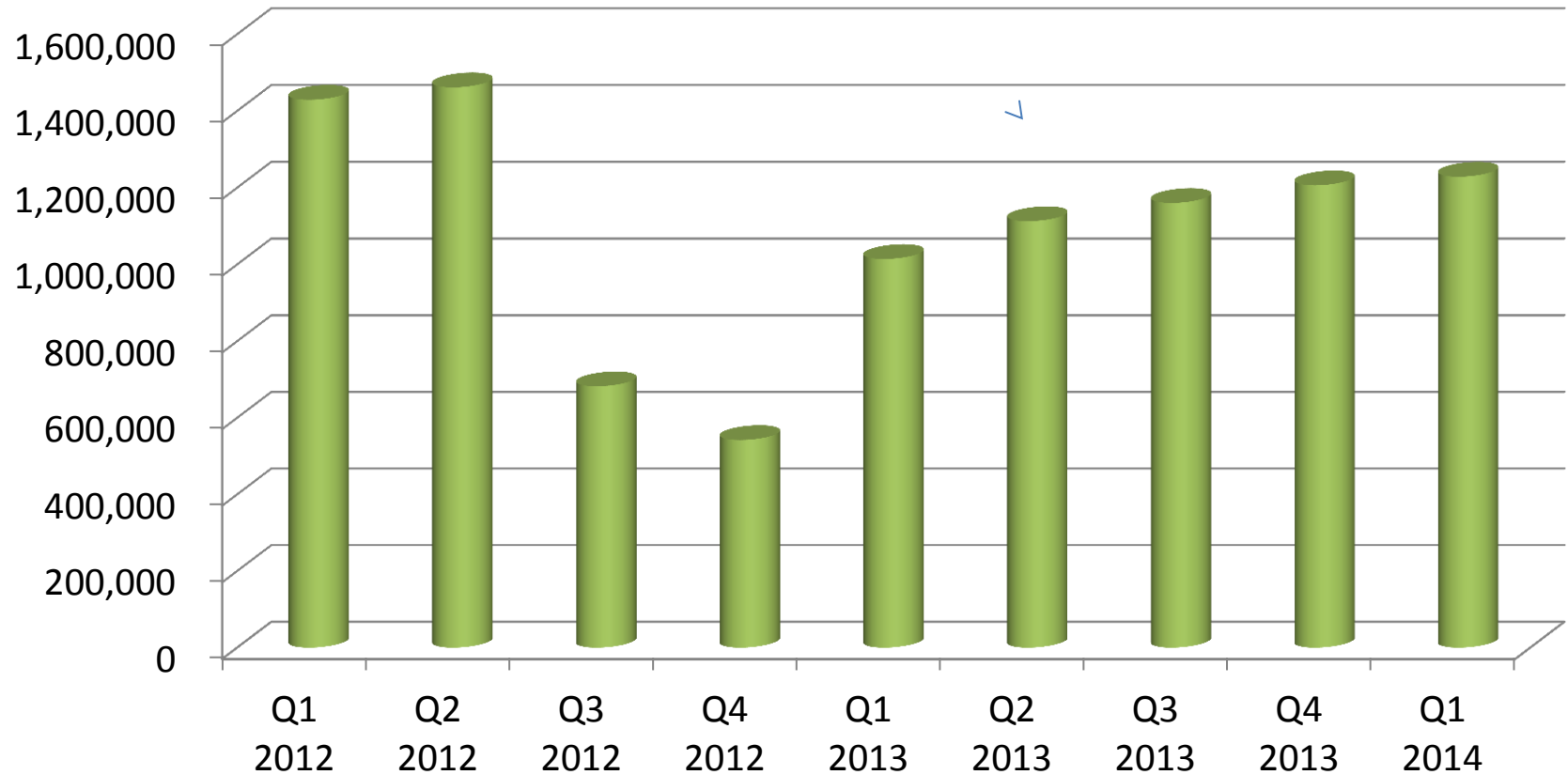
Growth Driver:
Advanced processes & market-share raise

Industry Sales Breakdown: Green Energy 綠能營收

綠能產業

Green Energy Industry

千元
In thousands

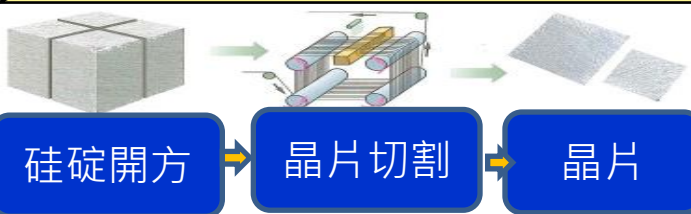


2012 Q1	2012 Q2	2012 Q3	2012 Q4	2013 Q1	2013 Q2	2013 Q3	2013 Q4	2014 Q1
1,429,243	1,461,628	682,358	542,194	1,014,297	1,112,908	1,160,422	1,206,350	1,228,753

Solar Supply Chain

太陽能產業鏈

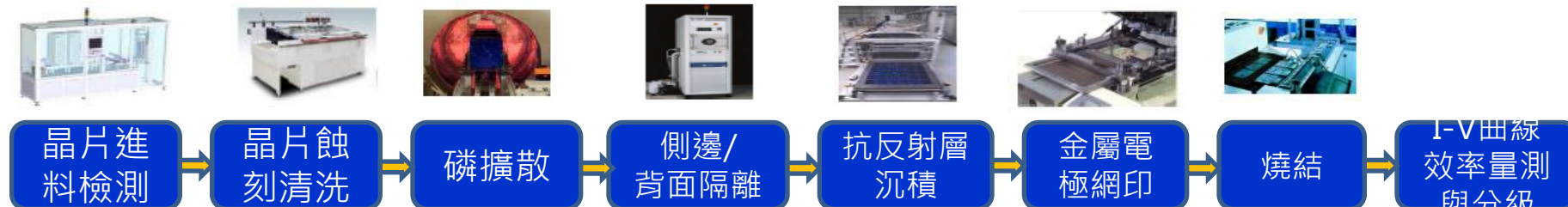
Solar Wafer



• 切割鋼線 Wire

- 多晶矽晶片 Poly silicon wafer
- 單晶矽晶片 Single silicon wafer

Solar Cell



- NF3
- IC Chemical
- Texture etchant
- POCL3

- NH3
- SiH4

- 銀漿、鋁漿 Ag Paste, Al Paste
- 銀/鋁漿 Ag/Al Paste

PV Module



- Solar Cell

- Solar Glass
- Back sheet
- EVA sheet

- Junction Box 用PPE

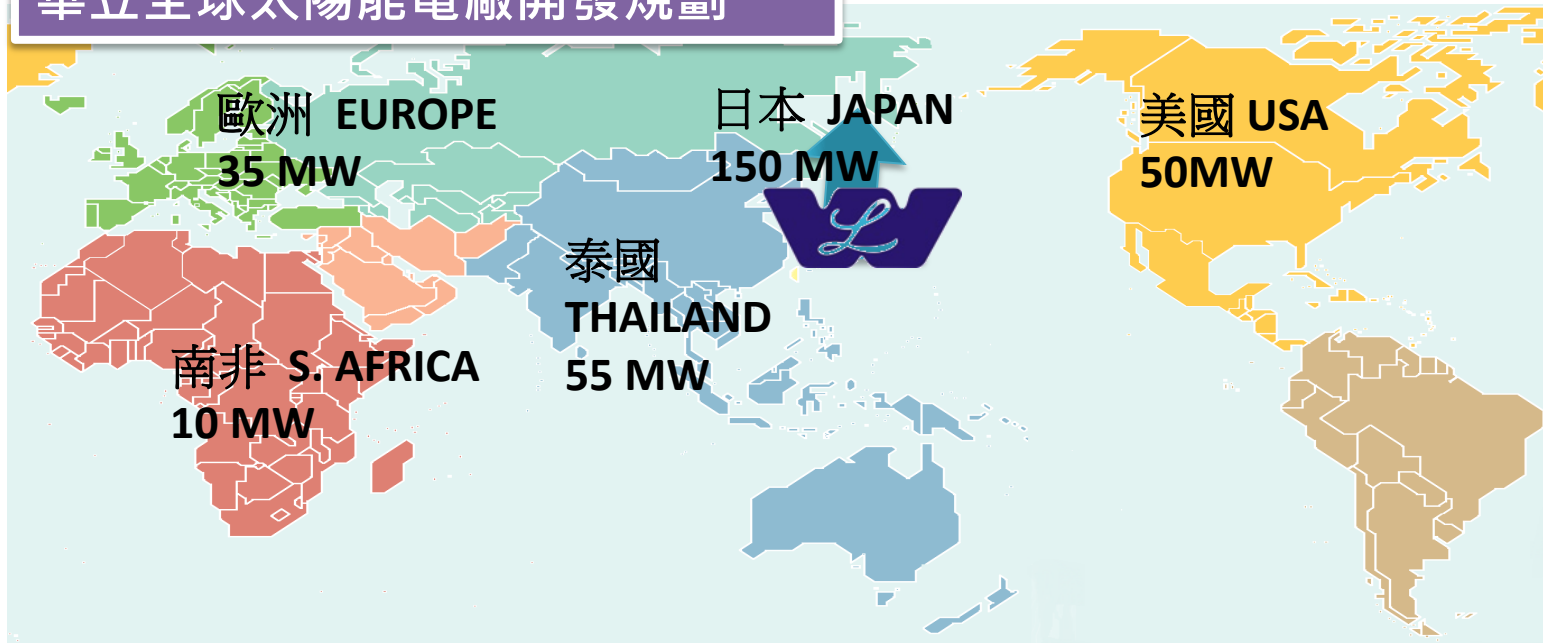
TV System

- 小型太陽能系統 System
- 電廠 Solar Plants

WL's Growth Driver in Solar WL太陽能的成長動能

- 更具彈性的服務模式 Flexible Service Model
 - 除單晶、多晶、銀鋁漿、背板等材料銷售外，進行代工等服務與出海口機會，具備全面產業鏈供應能力 Besides such material sales as silicon wafer/cell/module, Ag/Al paste, back sheet and so on, WL provides a full range of services to the supply chain including OEM and turnkey solutions.
- 海外太陽能電廠營運與開發 Development and Operation of Solar Plants
 - 具備當地市場開發與建置能力 Local market development and EPC (engineering, procurement and construction)
 - 與金融集團合作取得資金槓桿 Cooperation with financial groups for capital leverage

華立全球太陽能電廠開發規劃

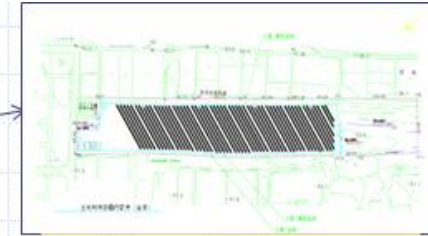


Solar Plants in Japan 日本太陽能電廠建置

- 搶先把握每度40日圓高收購電價，華立在日本中部地區建置5MW 電廠：Wah Lee established 5 MW solar plants in Japan:
 - 石川縣2MW在2013/08併網售電
Ishikawa Plant (2MW) started generating electricity sales in Aug. 2013 .
 - 富山縣3MW在2014/02併網售電
Toyama Plant (3MW) are projected to generate electricity sales in Feb. 2014.
- 尚有超過50MW的日本電廠案正在洽談中，華立將持續擴大太陽能出海口的發展，提升供應鏈整體銷售的獲利 More than 50MW projects are under development.



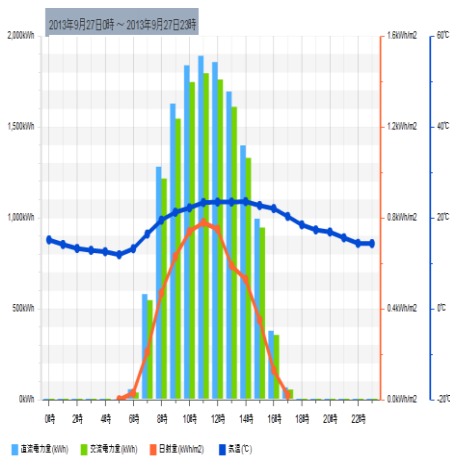
中部地區地圖
案件1-石川縣內灘町
案件2-富山縣高岡市



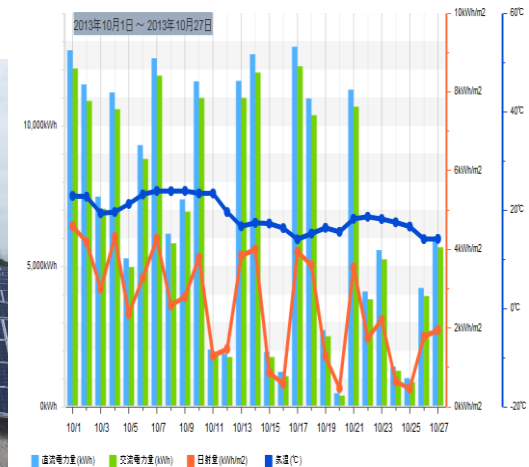
案件1-石川縣內灘町-2MW



案件2-富山縣高岡市-3MW



2013/9/2 Power Statistics

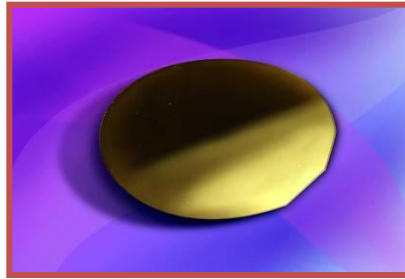


2013/10 Power Statistics

LED Supply Chain

LED產業鏈

1. 原始材料合成
2. 蒸餾還原形成多晶
3. 單晶成長單晶棒



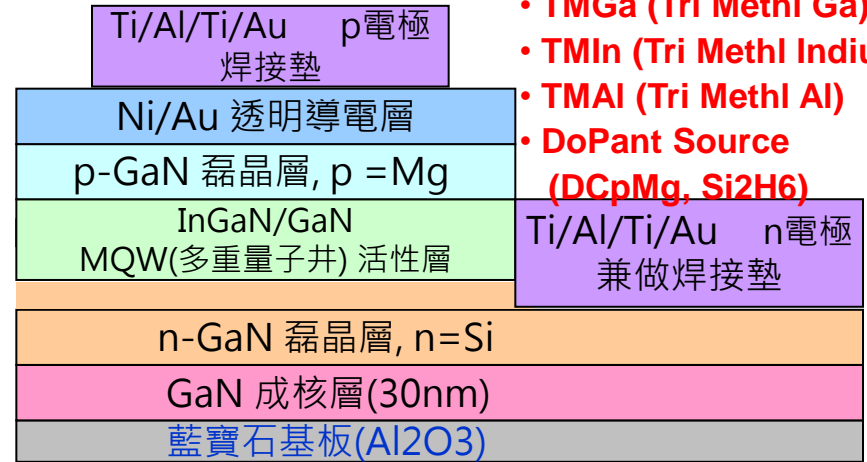
將單晶棒鋸切成片狀晶圓，並加以拋光處理。

- 鑽石切割線、PSS

4. 晶圓/基板

N電極形成區

- AsH₃、PH₃、SiH₄



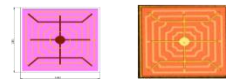
- NH₃、GaAs
- TMGa (Tri Methl Ga)
- TMIIn (Tri Methl Indium)
- TMAI (Tri Methl Al)
- DoPant Source (DCpMg, Si₂H₆)

5. 磊晶成長

6. 晶片製程 (製作電極圖案)

- Du Pont EKC Remover

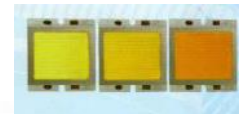
7. 磊晶晶圓減薄並切割成晶粒



- EMITTER

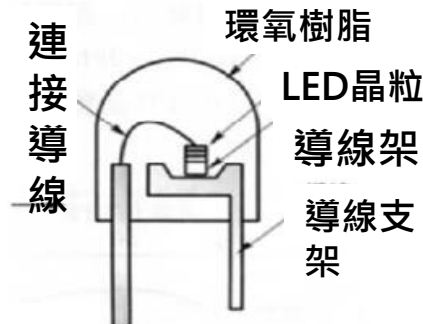
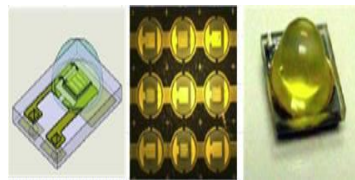
9. 元件/模組

8. 封裝



10. 半成品/成品

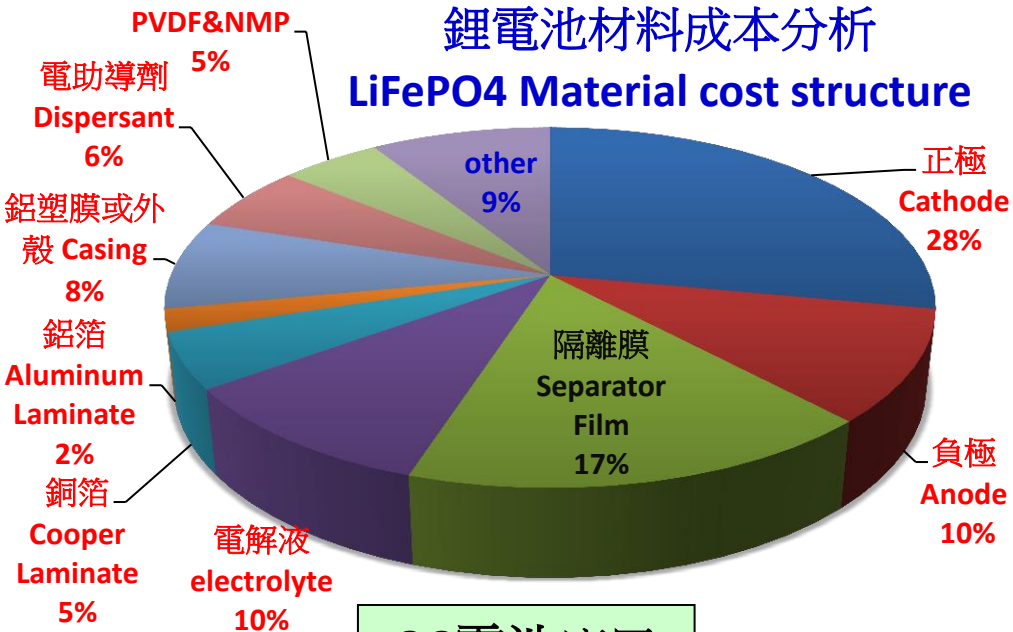
- 構構件
- 燈源/燈具



- PA9T、LCP
- 螢光粉
- 封裝材(矽膠、Hybrid、Epoxy)
- JSR LED Material

Products in Rechargeable Battery 二次電池產品

鋰電池材料成本分析
LiFePO4 Material cost structure



動力電池應用 Power Application



電動車
Electric Vehicle



電動機車 E-bike



充電站 Charging Station

電池模組 Module



3C電池芯
Battery Cell



電動車電池模組
Electric Vehicle Module



平板電池模組
Tablet Battery Cell

3C電池應用 3C Application



平板 Tablet



智慧型手機
Smart Phone



平板電腦
Tablet PC



無線充電電池系統
Wireless Charging System

Biotech Roadmap 生化產業發展規劃



製藥 Pharmaceutical	日商/賦形劑 Japan/Excipient	
生化 Biomedical	日商/生化原料 Japan/ Biomedical Material	
	台商/生化原料 Taiwan/ Biomedical Material (談代理權中)	
	台商/飼料用生化原料 Taiwan/ Biotech Material (已投資&取得銷售權)	
醫材 Medical Tools/ Equipment	日商/塑膠原料&膠材 Plastic Materials in China	
	台商/一,二級醫材 – Medical Related Material 日商/手術器材 Japan/ Surgery Tools 台商&日商/醫療服務醫材(大陸Project)in China	
保健食品 Dietary Supplements	台商/保健食品 Taiwan	
	日商/原料,保健食品(評估代理) Japan	

2014Q1 Consolidated Income Statement 合併損益表

Unit: NT\$ million	2014Q1 (CPA)	2013Q1 (CPA)	YoY	2014Q1 as % of Full 2013
Net Sales 營收淨額	8,870.9	7,625.5	16%	25.8%
Gross Profit 銷貨毛利	792.5	671.4	18%	25.5%
Gross Margin 毛利率	8.9%	8.8%	0.1%	
Op. Expense 營業費用	506.5	465.6	9%	24.3%
Op. Profit 營業利益	286.1	205.8	39%	28.1%
Non-op. Profit 業外收支	79.0	156.4	-49%	12.7%
L-T investment income 長投收益	81.7	87.0	-6%	26.8%
Disposal gain 處分利益	44.9	15.3	194%	56.3%
Others 其他	(47.5)	54.1	-188%	-20.2%
Pre-tax Profit 稅前利潤	365.1	362.2	1%	22.3%
Net Income 稅後淨利	289.4	286.5	1%	23.4%
After tax EPS	1.25	1.24	1%	25.0%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

2014Q1 Long Term Investments 長期投資收益

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2014Q1 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	28	34,169
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	24,866
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	26	19,795
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	2,822
Total			81,652

2014Q1 Consolidated Balance Sheet 合併資產負債表

Unit: NT\$ million

	2014-03-31 (CPA)		2013-03-31 (CPA)			2014-03-31 (CPA)		2013-03-31 (CPA)	
Cash & Equiv. 現金	2,893	12.1%	1,941	9.2%	S-T Borrowing 短期借款	4,532	19.0%	4,123	19.6%
A/R 應收帳款	9,879	41.5%	8,683	41.2%	A/P 應付帳款	6,258	26.3%	5,121	24.3%
Inventory 存貨	3,281	13.8%	2,687	12.8%	Other C/L 其他流動負債	346	1.5%	173	0.8%
Other C/A 其他流動資產	1,562	6.6%	1,840	8.7%	Current Liab. 流動負債	11,135	46.8%	9,417	44.7%
Current Assets 流動資產	17,614	74.0%	15,151	72.0%	L-T Liab. 長期負債	1,847	7.8%	1,559	7.4%
Financial Asset-Non Current 金融資產-非流動	247	1%	599	2.8%	Other Liab. 其他負債	901	3.8%	787	3.7%
L-T investments 長期投資	4,108	17.2%	3,883	18.4%	Non-Current Liab. 非流動負債	2,748	11.5%	2,347	11.1%
Fixed Assets 固定資產	1,373	5.8%	975	4.6%	Total Liab. 總負債	13,883	58.3%	11,763	55.9%
Other Assets 其他資產	474	2.0%	448	2.1%	Capital 股本	2,314	9.7%	2,314	11.0%
Non-Current Asset 非流動資產	6,201	26.0%	5,905	28.0%	Capital Surplus 資本公積	1,260	5.3%	1,266	6.0%
					Retained Earnings 保留盈餘	5,319	22.3%	4,725	22.4%
					Other Equities 其他權益	318	1.3%	383	1.8%
					Non-Controlling. Interest 非控制權益	722	3.0%	604	2.9%
Total Assets 總資產	23,815	100.0%	21,056	100.0%	Total Equities 總股東權益	9,932	41.7%	9,292	44.1%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

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Consolidated Financial Indicators 合併財務比率

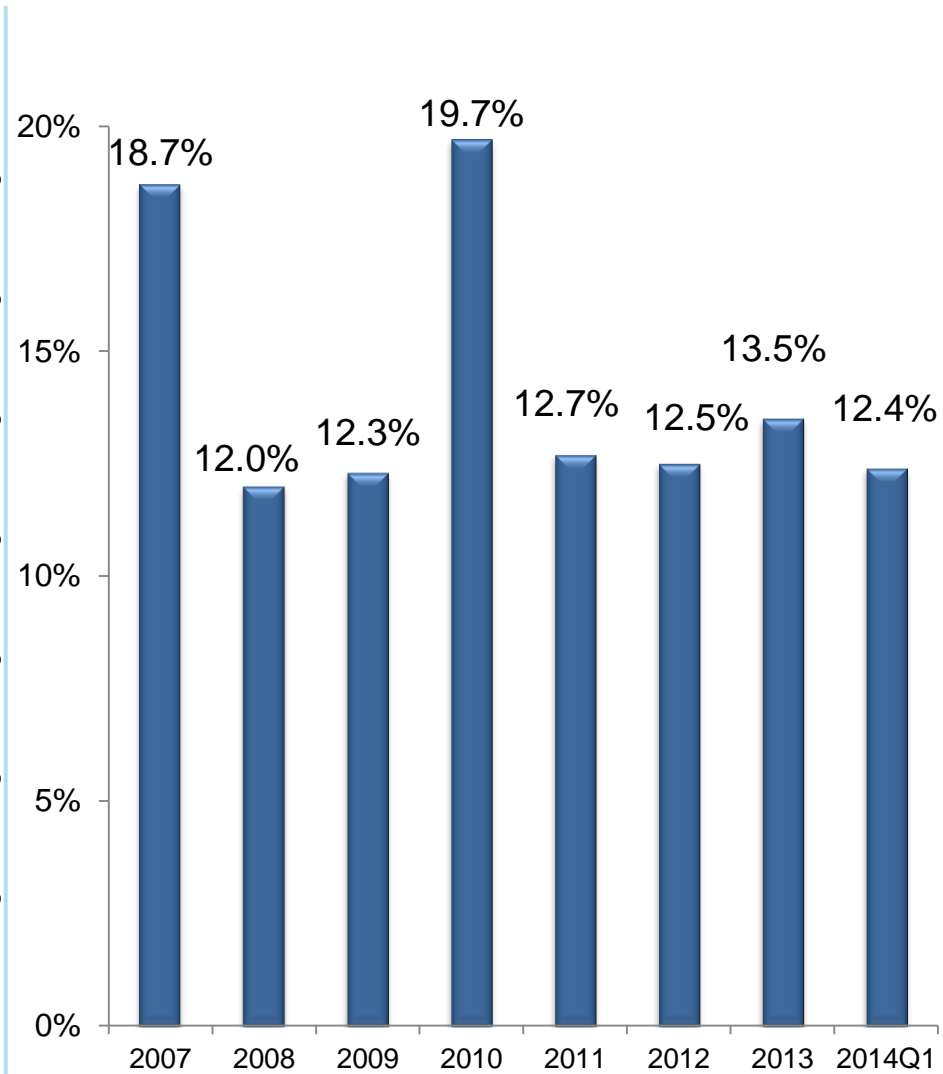
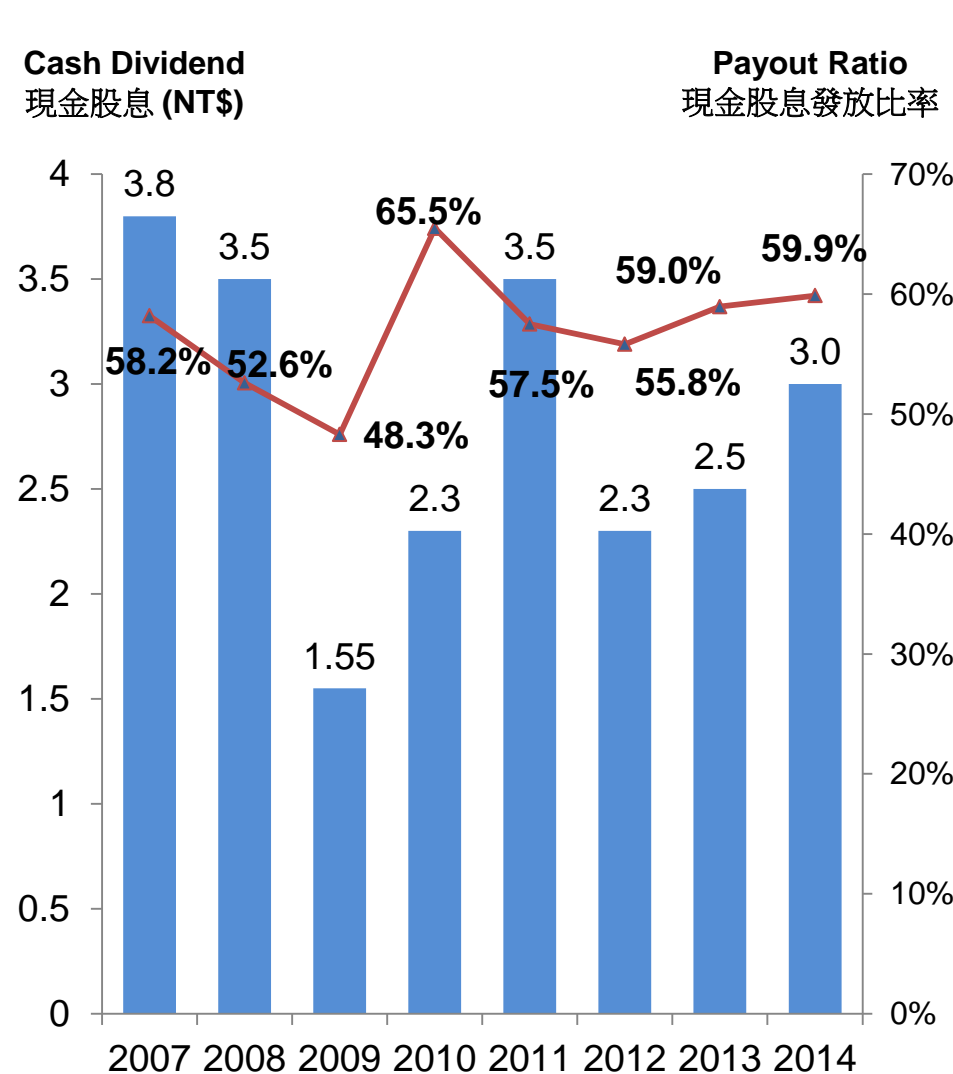
	2007	2008	2009	2010	2011	2012	2013	2014Q1
Current Ratio 流動比率	144.8%	148.6%	171.7%	162.6%	164.4%	162.2%	158.2%	158.2%
Quick Ratio 速動比率	98.8%	95.6%	132.4%	115.9%	122.2%	130.9%	127.7%	125.8%
Net Debt/Equity 淨負債比率	36.2%	42.3%	9.0%	22.3%	31.0%	20.7%	17.4%	23.3%
A/R days 應收帳款天數	84.8	86.3	102.1	87.9	88.9	95.2	96.2	99.7
Inventory days 存貨天數	53.4	64.8	69.6	47.6	46.2	40.7	35.6	38.1
A/P days 應付帳款天數	57.9	54.2	62.7	61.2	56.8	58.9	62.0	63.0
Cash conversion days 現金週轉天數	80.3	96.9	108.9	74.4	78.2	76.9	69.8	74.8
Operating cash flow (NT\$K) 來自營業活動現金流量	243,444	636,700	2,539,747	-389,836	603,661	1,444,741	855,991	-591,047
ROE 股東權益報酬率	18.7%	12.0%	12.3%	19.7%	12.7%	12.5%	13.5%	12.4%

* ROE of 2014Q1 is annualized.

Shareholder Returns Trend 股東投資報酬

Dividend Policy 股利政策

ROE 股東權益報酬率



* Dividends are distribution of prior year's earnings.

* 2014 dividends are subject to AGM's approval.

* ROE of 2014Q1 is annualized.

2013 Consolidated Income Statement 合併損益表

Unit: NT\$ million	2013 (CPA)	2012 (CPA)	YoY
Net Sales 營收淨額	34,398.4	31,545.3	9%
Gross Profit 銷貨毛利	3,104.1	2,857.9	9%
Gross Margin 毛利率	9.0%	9.1%	0.0%
Op. Expense 營業費用	2,085.4	2,014.3	4%
Op. Profit 營業利益	1,018.8	843.6	21%
Non-op. Profit 業外收支	620.0	479.6	29%
L-T investment income 長投收益	304.8	415.7	-27%
Disposal gain 處分利益	79.7	4.1	1845%
Others 其他	235.5	59.8	294%
Pre-tax Profit 稅前利潤	1,638.8	1,323.2	24%
Net Income 稅後淨利	1,159.5	987.8	17%
After tax EPS	5.01	4.27	17%

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2013 Long Term Investments 長期投資收益

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2013 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	28	138,430
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	128,508
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	26	23,529
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	14,295
Total			304,762

2013 Consolidated Balance Sheet 合併資產負債表

Unit: NT\$ million

	2013-12-31 (CPA)		2012-12-31 (CPA)			2013-12-31 (CPA)		2012-12-31 (CPA)	
Cash & Equiv. 現金	3,339	14.4%	1,739	8.5%	S-T Borrowing 短期借款	4,143	17.9%	3,632	17.8%
A/R 應收帳款	9,514	41.1%	8,614	42.3%	A/P 應付帳款	6,386	27.6%	5,470	26.9%
Inventory 存貨	3,081	13.3%	2,650	13.0%	Other C/L 其他流動負債	264	1.1%	191	0.9%
Other C/A 其他流動資產	1,140	4.9%	1,929	9.5%	Current Liab. 流動負債	10,793	46.7%	9,293	45.6%
Current Assets 流動資產	17,074	73.8%	14,931	73.3%	L-T Liab. 長期負債	1,800	7.8%	1,561	7.7%
Financial Asset-Non Current 金融資產-非流動	245	1%	546	2.7%	Other Liab. 其他負債	878	3.8%	764	3.8%
L-T investments 長期投資	4,008	17.3%	3,511	17.2%	Non-Current Liab. 非流動負債	2,678	11.6%	2,326	11.4%
Fixed Assets 固定資產	1,344	5.8%	1,009	5.0%	Total Liab. 總負債	13,471	58.2%	11,618	57.0%
Other Assets 其他資產	456	2.0%	370	1.8%	Capital 股本	2,314	10.0%	2,314	11.4%
Non-Current Asset 非流動資產	6,053	26.2%	5,435	26.7%	Capital Surplus 資本公積	1,260	5.4%	1,246	6.1%
					Retained Earnings 保留盈餘	5,029	21.7%	4,439	21.8%
					Other Equities 其他權益	343	1.5%	174	0.9%
					Non-Controlling. Interest 非控制權益	710	3.1%	575	2.8%
Total Assets 總資產	23,127	100.0%	20,366	100.0%	Total Equities 總股東權益	9,656	41.8%	8,748	43.0%

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